MV0520X

# 200W, HF-200MHz 28V High Power RF LDMOS

## **Description**

The MV0520X is a 200W single ended 28V LDMOS, highly rugged, unmatched for any applications within HF-200MHz

It supports CW, and pulsed and any modulated signal at either saturated or linear application.

It is also intended to be the drop-in replacement of legacy VDMOS such as D1017UK etc in the same mechanical outline while with improved performance

•Typical Performance (On Innogration fixture with device soldered):

 $V_{DD}$  = 28 Volts,  $I_{DQ}$  = 150 mA, CW.

Frequency	Pin (dBm)	Gp (dB)	P <sub>OUT</sub> (W)	η <sub>D</sub> (%)
40.68MHz	33	20	203	81

## **Features**

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Excellent thermal stability, low HCI drift
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

## **Suitable Applications**

- 2-30MHz (HF or Short wave communication)
- 30-88MHz (Ground communication)
- 54-88MHz (TV VHF I)
- 88-108MHz (FM)
- 118 -140MHz (Avionics)

- 136-174MHz (Commercial ground communication)
- 160-230MHz (TV VHF III)

**Table 1. Maximum Ratings** 

Rating	Symbol	Value	Unit
DrainSource Voltage	V <sub>DSS</sub>	+95	Vdc
GateSource Voltage	V <sub>GS</sub>	-10 to +10	Vdc
Operating Voltage	V <sub>DD</sub>	+36	Vdc
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	TJ	+225	°C

#### **Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case	Para 0.55	0.55	°C/W
T <sub>C</sub> = 85°C, T <sub>J</sub> =200°C, DC test	Rejc	0.55	-0/00

#### **Table 3. ESD Protection Characteristics**

Test Methodology	Class
Human Body Model (per JESD22A114)	Class 2

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**Table 4. Electrical Characteristics** (TA = 25  $^{\circ}$ C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OC Characteristics					
Drain-Source Voltage	V	95			V
V <sub>GS</sub> =0, I <sub>DS</sub> =1.0mA	V <sub>(BR)DSS</sub>				V
Zero Gate Voltage Drain Leakage Current				4	
$(V_{DS} = 75V, V_{GS} = 0 V)$	I <sub>DSS</sub>			1	μА
Zero Gate Voltage Drain Leakage Current				1	
$(V_{DS} = 28 \text{ V}, V_{GS} = 0 \text{ V})$	I <sub>DSS</sub>			1	μА
GateSource Leakage Current				1	
$(V_{GS} = 10 \text{ V}, V_{DS} = 0 \text{ V})$	I <sub>GSS</sub>				μА
Gate Threshold Voltage	V (0)		2.2		V
$(V_{DS} = 28V, I_D = 400 \mu A)$	V <sub>GS</sub> (th)				V
Gate Quiescent Voltage	V	V <sub>GS(Q)</sub> ———	3.05		V
$(V_{DD} = 28 \text{ V}, I_D = 150 \text{ mA}, \text{Measured in Functional Test})$	V <sub>GS(Q)</sub>				v
Common Source Input Capacitance	$C_{ISS}$		187		,,,
$(V_{GS} = 0V, V_{DS} = 28 V, f = 1 MHz)$	Ciss		107		pF
Common Source Output Capacitance			70		"F
$(V_{GS} = 0V, V_{DS} = 28 V, f = 1 MHz)$	Coss		79		pF
Common Source Feedback Capacitance			4.6		pF
$(V_{GS} = 0V, V_{DS} = 28 V, f = 1 MHz)$	$C_{RSS}$		4.6		

Power Gain	Gp	 20	 dB
Drain Efficiency@Pout	η <sub>D</sub>	 80	 %
Output Power	P <sub>out</sub>	 200	 W
Input Return Loss	IRL	 -7	 dB

Load Mismatch (In Innogration Test Fixture, 50 ohm system): V<sub>DD</sub> = 28 Vdc, I<sub>DQ</sub> = 150 mA, f = 150 MHz

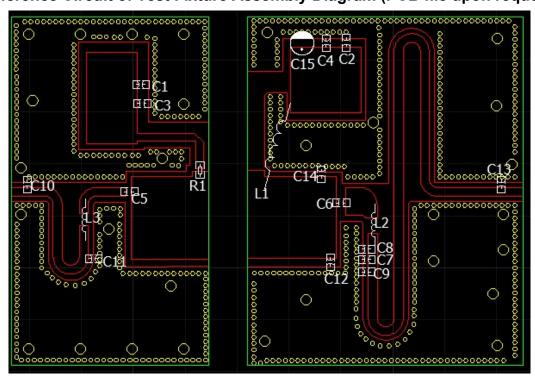
ſ	VSWR 20:1 at 200W pulse CW Output Power	No Device Degradation

#### TYPICAL CHARACTERISTICS

Figure 1: Network analyzer output S11/221



### Reference Circuit of Test Fixture Assembly Diagram (PCB file upon request)



# **MV0520X LDMOS TRANSISTOR**

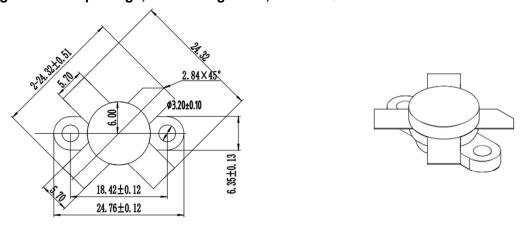
Table 1. Test Circuit Component Designations and Values (40.68MHz)

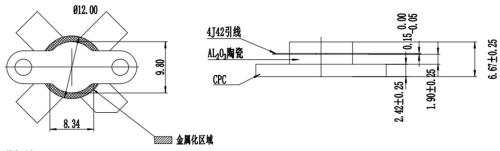
Component	Description	Suggestion
C1,C2	10uF	10uF/100V
C3~C6	10nF	10nF/100V
C7,C8	150pF	MQ101111
C9	39pF	MQ101111
C10	120pF	MQ101111
C11	47pF	MQ101111
C12	18pF	MQ101111
C13	12pF	MQ101111
C14	200pF	MQ101111
C15	470uF/63V	Electrolytic Capacitor
R1	10 Ω	Chip Resistor
L1	1.5mm/5mm,8 turns	
L2	1.5mm/5mm,4 turns	
L3	1.5mm/5mm, 6 turns	
PCB	30Mil	Rogers4350

# **MV0520X LDMOS TRANSISTOR**

# **Package Outline**

Flanged ceramic package; 2 mounting holes; 2 leads (1—Gate、2—Drain、3—Source)





技术要求:

- 1. 未注尺寸公差±0.15;
- 2. 全镀金: 外底面、内腔以及引线中心Ni:2.54-11.43 μm, 金2.54-4 μm;
- 3. 图示阴影部分为金属化区。
- 4. 单位:mm.

# **Revision history**

Table 5. Document revision history

Date	Revision	Datasheet Status
2021/3/26	Rev 1.0	Preliminary datasheet

Applicaion data based on TC-24-22

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